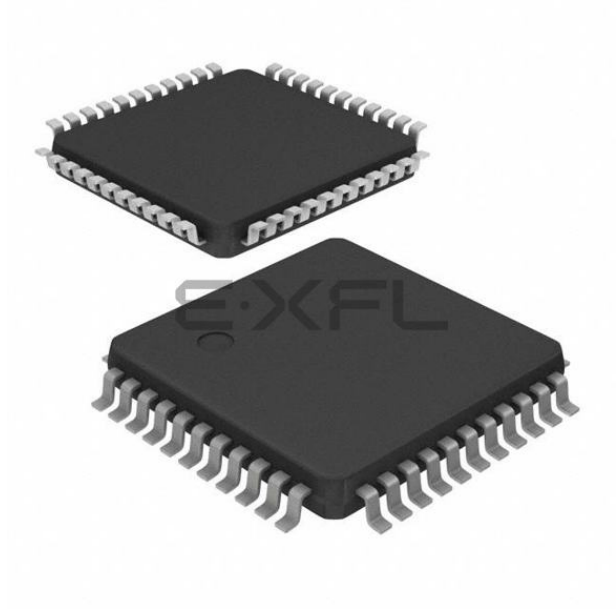

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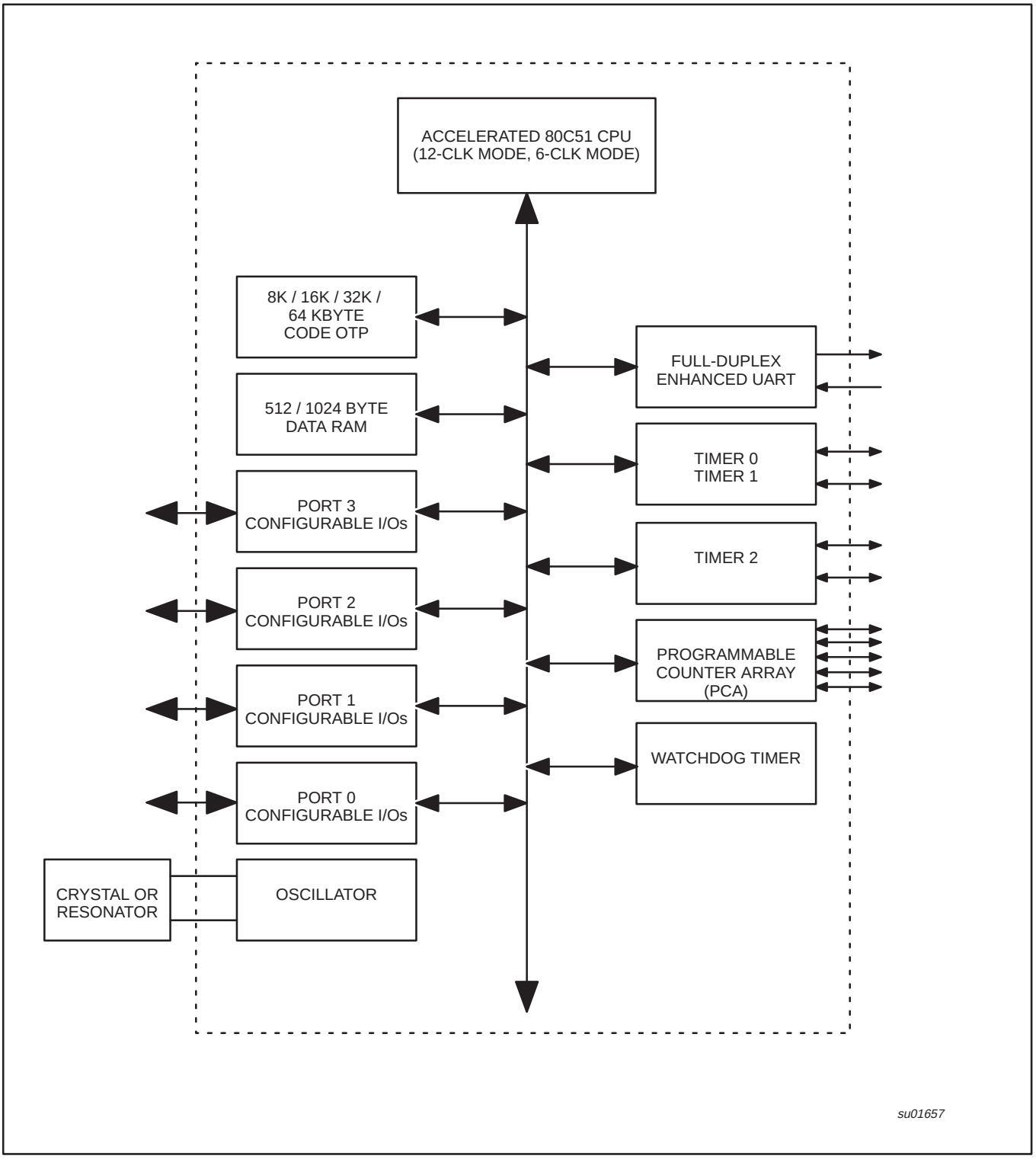
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	8051
Core Size	8-Bit
Speed	33MHz
Connectivity	EBI/EMI, UART/USART
Peripherals	POR, PWM, WDT
Number of I/O	32
Program Memory Size	32KB (32K x 8)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	44-LQFP
Supplier Device Package	44-LQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/p87c51rc2bbd-157

BLOCK DIAGRAM 1



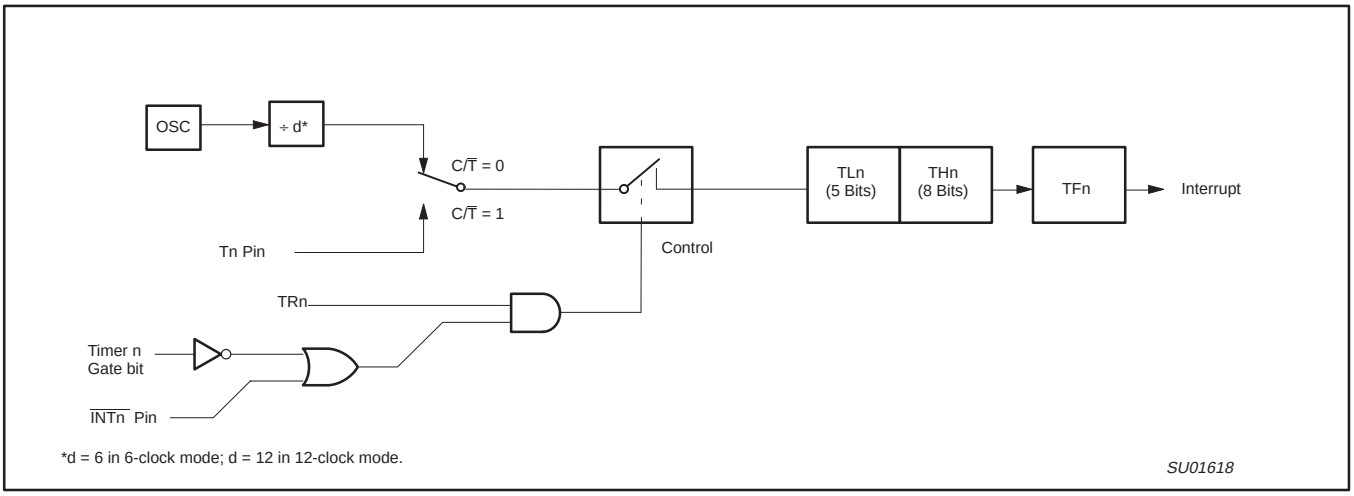


Figure 3. Timer/Counter 0/1 Mode 0: 13-Bit Timer/Counter

TCON Address = 88H Reset Value = 00H

Bit Addressable

7	6	5	4	3	2	1	0
TF1	TR1	TF0	TR0	IE1	IT1	IE0	IT0

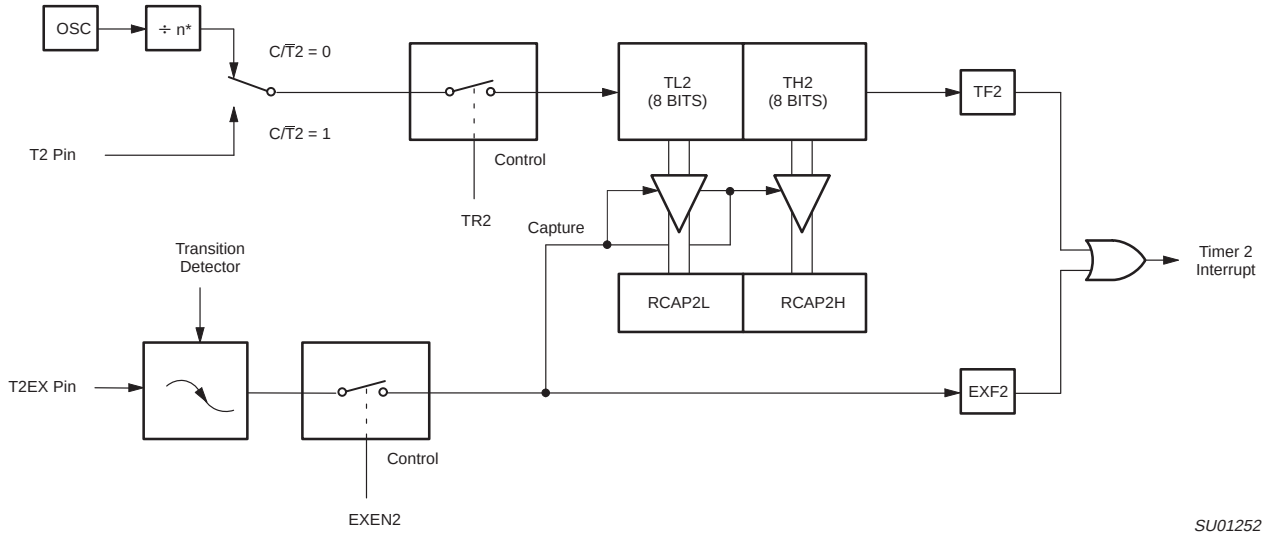
BIT	SYMBOL	FUNCTION
TCON.7	TF1	Timer 1 overflow flag. Set by hardware on Timer/Counter overflow. Cleared by hardware when processor vectors to interrupt routine, or clearing the bit in software.
TCON.6	TR1	Timer 1 Run control bit. Set/cleared by software to turn Timer/Counter on/off.
TCON.5	TF0	Timer 0 overflow flag. Set by hardware on Timer/Counter overflow. Cleared by hardware when processor vectors to interrupt routine, or by clearing the bit in software.
TCON.4	TR0	Timer 0 Run control bit. Set/cleared by software to turn Timer/Counter on/off.
TCON.3	IE1	Interrupt 1 Edge flag. Set by hardware when external interrupt edge detected. Cleared when interrupt processed.
TCON.2	IT1	Interrupt 1 type control bit. Set/cleared by software to specify falling edge/low level triggered external interrupts.
TCON.1	IE0	Interrupt 0 Edge flag. Set by hardware when external interrupt edge detected. Cleared when interrupt processed.
TCON.0	IT0	Interrupt 0 Type control bit. Set/cleared by software to specify falling edge/low level triggered external interrupts.

SU01516

Figure 4. Timer/Counter 0/1 Control (TCON) Register

Table 3. Timer 2 Operating Modes

RCLK + TCLK	CP/$\overline{RL2}$	TR2	MODE
0	0	1	16-bit Auto-reload
0	1	1	16-bit Capture
1	X	1	Baud rate generator
X	X	0	(off)



* n = 6 in 6-clock mode, or 12 in 12-clock mode.

Figure 2. Timer 2 in Capture Mode

T2MOD Address = 0C9H Reset Value = XXXX XX00B

Not Bit Addressable

—	—	—	—	—	—	T2OE	DCEN
Bit 7	6	5	4	3	2	1	0

Symbol	Function
—	Not implemented, reserved for future use.*
T2OE	Timer 2 Output Enable bit.
DCEN	Down Count Enable bit. When set, this allows Timer 2 to be configured as an up/down counter.

* User software should not write 1s to reserved bits. These bits may be used in future 8051 family products to invoke new features. In that case, the reset or inactive value of the new bit will be 0, and its active value will be 1. The value read from a reserved bit is indeterminate.

SU00729

Figure 3. Timer 2 Mode (T2MOD) Control Register

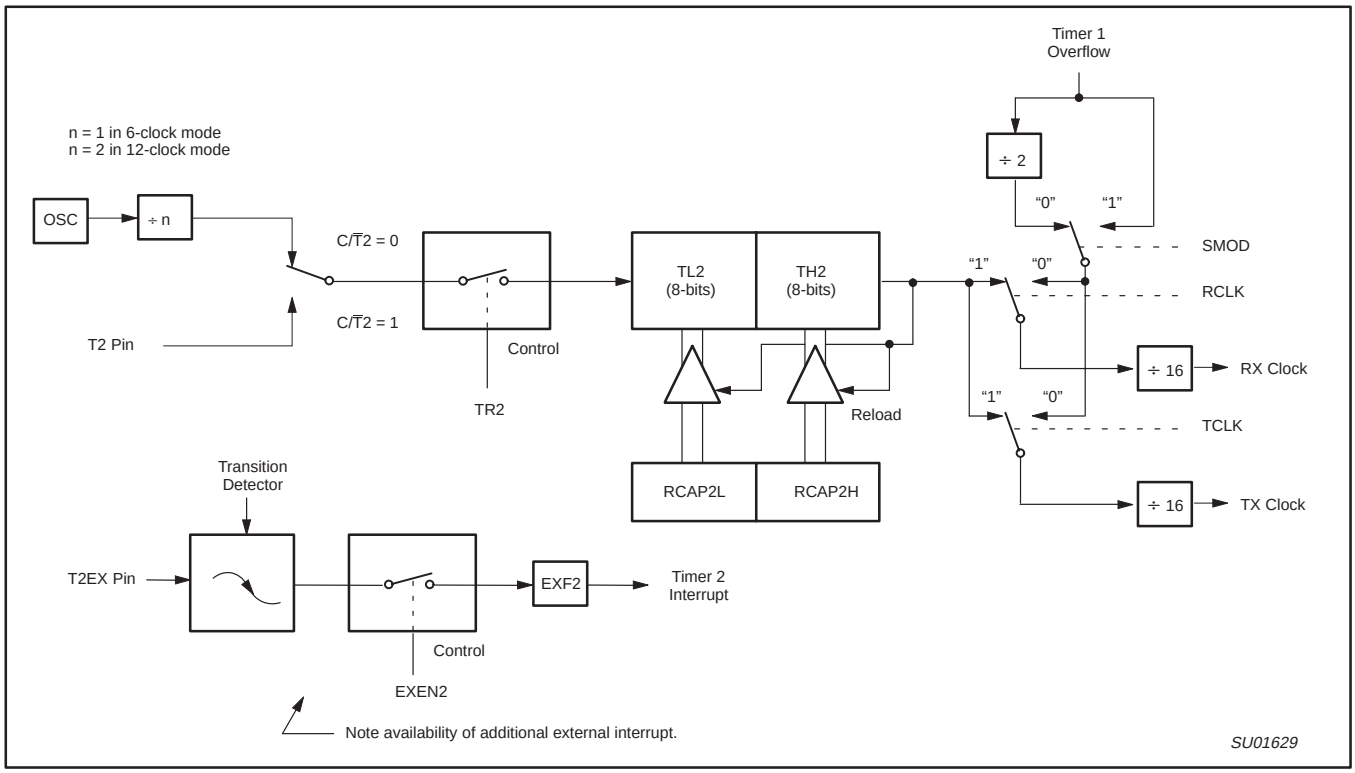


Figure 6. Timer 2 in Baud Rate Generator Mode

Table 4. Timer 2 Generated Commonly Used Baud Rates

Baud Rate		Osc Freq	Timer 2	
12-clock mode	6-clock mode		RCAP2H	RCAP2L
375 k	750 k	12 MHz	FF	FF
9.6 k	19.2 k	12 MHz	FF	D9
4.8 k	9.6 k	12 MHz	FF	B2
2.4 k	4.8 k	12 MHz	FF	64
1.2 k	2.4 k	12 MHz	FE	C8
300	600	12 MHz	FB	1E
110	220	12 MHz	F2	AF
300	600	6 MHz	FD	8F
110	220	6 MHz	F9	57

Baud Rate Generator Mode

Bits TCLK and/or RCLK in T2CON (Table 4) allow the serial port transmit and receive baud rates to be derived from either Timer 1 or Timer 2. When TCLK= 0, Timer 1 is used as the serial port transmit baud rate generator. When TCLK= 1, Timer 2 is used as the serial port transmit baud rate generator. RCLK has the same effect for the serial port receive baud rate. With these two bits, the serial port can have different receive and transmit baud rates – one generated by Timer 1, the other by Timer 2.

Figure 6 shows the Timer 2 in baud rate generation mode. The baud rate generation mode is like the auto-reload mode,in that a rollover in TH2 causes the Timer 2 registers to be reloaded with the 16-bit value in registers RCAP2H and RCAP2L, which are preset by software.

The baud rates in modes 1 and 3 are determined by Timer 2's overflow rate given below:

$$\text{Modes 1 and 3 Baud Rates} = \frac{\text{Timer 2 Overflow Rate}}{16}$$

The timer can be configured for either "timer" or "counter" operation. In many applications, it is configured for "timer" operation (C/$\overline{T}$2=0). Timer operation is different for Timer 2 when it is being used as a baud rate generator.

Usually, as a timer it would increment every machine cycle (i.e., $^1/_6$ the oscillator frequency in 6-clock mode, $^1/_{12}$ the oscillator frequency in 12-clock mode). As a baud rate generator, it increments at the oscillator frequency in 6-clock mode ($^{OSC}/_2$ in 12-clock mode). Thus the baud rate formula is as follows:

$$\text{Modes 1 and 3 Baud Rates} = \frac{\text{Oscillator Frequency}}{[\,n^* \times [65536 - (\text{RCAP2H, RCAP2L})]]}$$

* n = 16 in 6-clock mode
32 in 12-clock mode

Where: (RCAP2H, RCAP2L)= The content of RCAP2H and RCAP2L taken as a 16-bit unsigned integer.

The Timer 2 as a baud rate generator mode shown in Figure 6, is valid only if RCLK and/or TCLK = 1 in T2CON register. Note that a rollover in TH2 does not set TF2, and will not generate an interrupt. Thus, the Timer 2 interrupt does not have to be disabled when Timer 2 is in the baud rate generator mode. Also if the EXEN2 (T2 external enable flag) is set, a 1-to-0 transition in T2EX (Timer/counter 2 trigger input) will set EXF2 (T2 external flag) but will not cause a reload from (RCAP2H, RCAP2L) to (TH2,TL2). Therefore when Timer 2 is in use as a baud rate generator, T2EX can be used as an additional external interrupt, if needed.

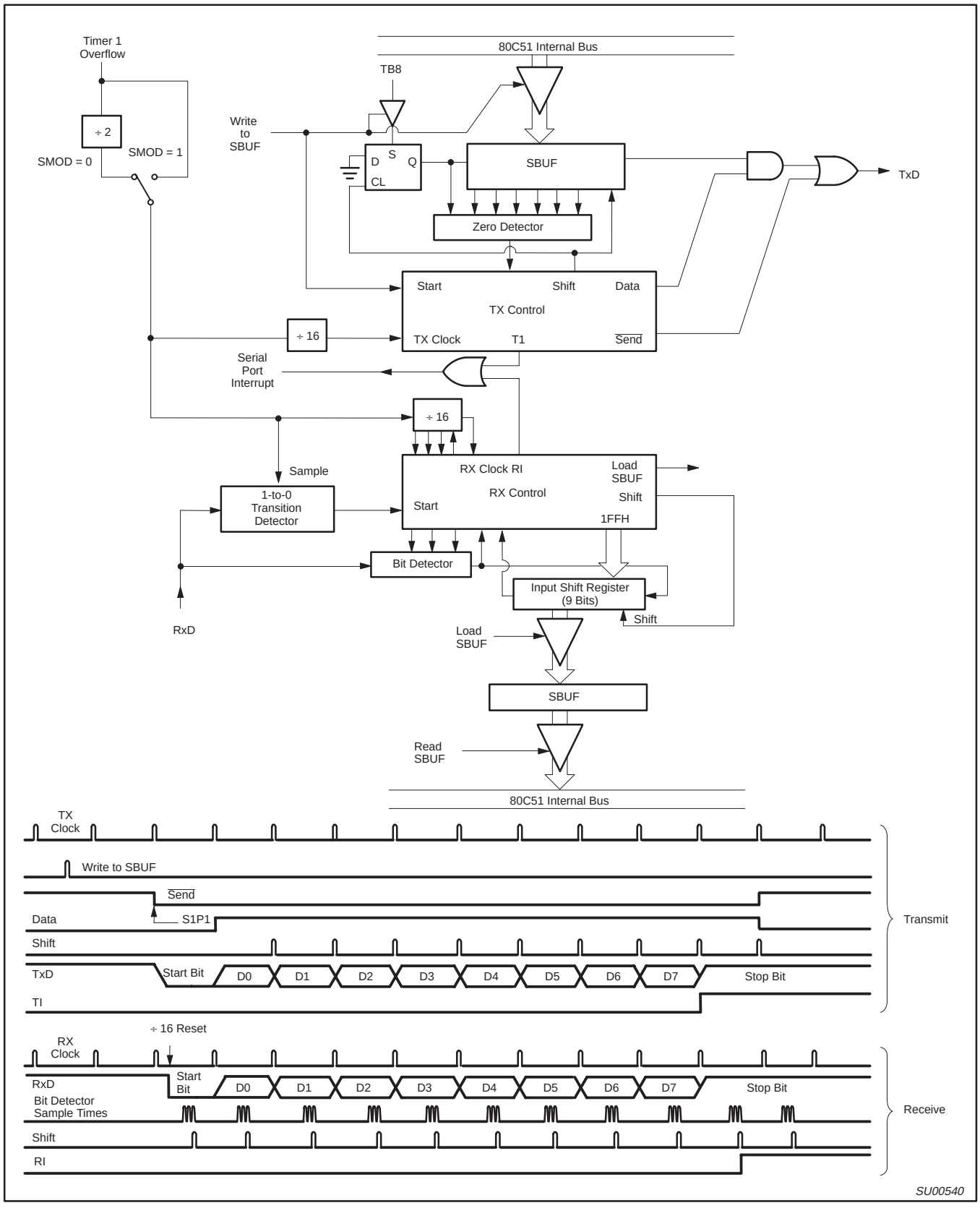


Figure 10. Serial Port Mode 1

	7	6	5	4	3	2	1	0
IP (0B8H)	–	PPC	PT2	PS	PT1	PX1	PT0	PX0

Priority Bit = 1 assigns high priority
Priority Bit = 0 assigns low priority

BIT	SYMBOL	FUNCTION
IP.7	–	–
IP.6	PPC	PCA interrupt priority bit
IP.5	PT2	Timer 2 interrupt priority bit.
IP.4	PS	Serial Port interrupt priority bit.
IP.3	PT1	Timer 1 interrupt priority bit.
IP.2	PX1	External interrupt 1 priority bit.
IP.1	PT0	Timer 0 interrupt priority bit.
IP.0	PX0	External interrupt 0 priority bit.

SU01291

Figure 16. IP Registers

	7	6	5	4	3	2	1	0
IPH (B7H)	–	PPCH	PT2H	PSH	PT1H	PX1H	PT0H	PX0H

Priority Bit = 1 assigns higher priority
Priority Bit = 0 assigns lower priority

BIT	SYMBOL	FUNCTION
IPH.7	–	–
IPH.6	PPCH	PCA interrupt priority bit
IPH.5	PT2H	Timer 2 interrupt priority bit high.
IPH.4	PSH	Serial Port interrupt priority bit high.
IPH.3	PT1H	Timer 1 interrupt priority bit high.
IPH.2	PX1H	External interrupt 1 priority bit high.
IPH.1	PT0H	Timer 0 interrupt priority bit high.
IPH.0	PX0H	External interrupt 0 priority bit high.

SU01292

Figure 17. IPH Registers

Reduced EMI Mode

The AO bit (AUXR.0) in the AUXR register when set disables the ALE output unless the CPU needs to perform an off-chip memory access.

Reduced EMI Mode

AUXR (8EH)

7	6	5	4	3	2	1	0
–	–	–	–	–	–	EXTRAM	AO

AUXR.1 EXTRAM
AUXR.0 AO

See more detailed description in Figure 32.

Dual DPTR

The dual DPTR structure (see Figure 18) is a way by which the chip will specify the address of an external data memory location. There are two 16-bit DPTR registers that address the external memory, and a single bit called DPS = AUXR1/bit0 that allows the program code to switch between them.

- New Register Name: AUXR1#
- SFR Address: A2H
- Reset Value: xxxxxxx0B

AUXR1 (A2H)

7	6	5	4	3	2	1	0
–	–	–	–	GF2	0	–	DPS

Where:
DPS = AUXR1/bit0 = Switches between DPTR0 and DPTR1.

Select Reg	DPS
DPTR0	0
DPTR1	1

The DPS bit status should be saved by software when switching between DPTR0 and DPTR1.

The GF2 bit is a general purpose user-defined flag. Note that bit 2 is not writable and is always read as a zero. This allows the DPS bit to be quickly toggled simply by executing an INC AUXR1 instruction without affecting the GF2 bit.

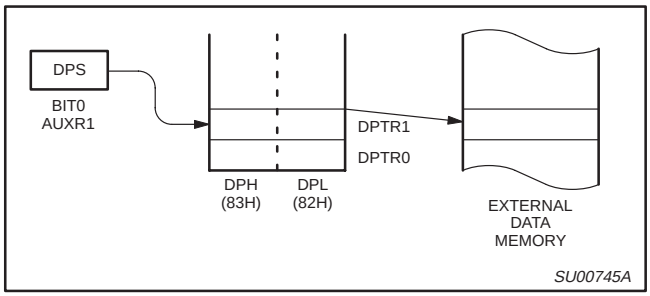


Figure 18.

DPTR Instructions

The instructions that refer to DPTR refer to the data pointer that is currently selected using the AUXR1/bit 0 register. The six instructions that use the DPTR are as follows:

INC DPTR	Increments the data pointer by 1
MOV DPTR, #data16	Loads the DPTR with a 16-bit constant
MOV A, @ A+DPTR	Move code byte relative to DPTR to ACC
MOVX A, @ DPTR	Move external RAM (16-bit address) to ACC
MOVX @ DPTR , A	Move ACC to external RAM (16-bit address)
JMP @ A + DPTR	Jump indirect relative to DPTR

The data pointer can be accessed on a byte-by-byte basis by specifying the low or high byte in an instruction which accesses the SFRs. See *Application Note AN458* for more details.

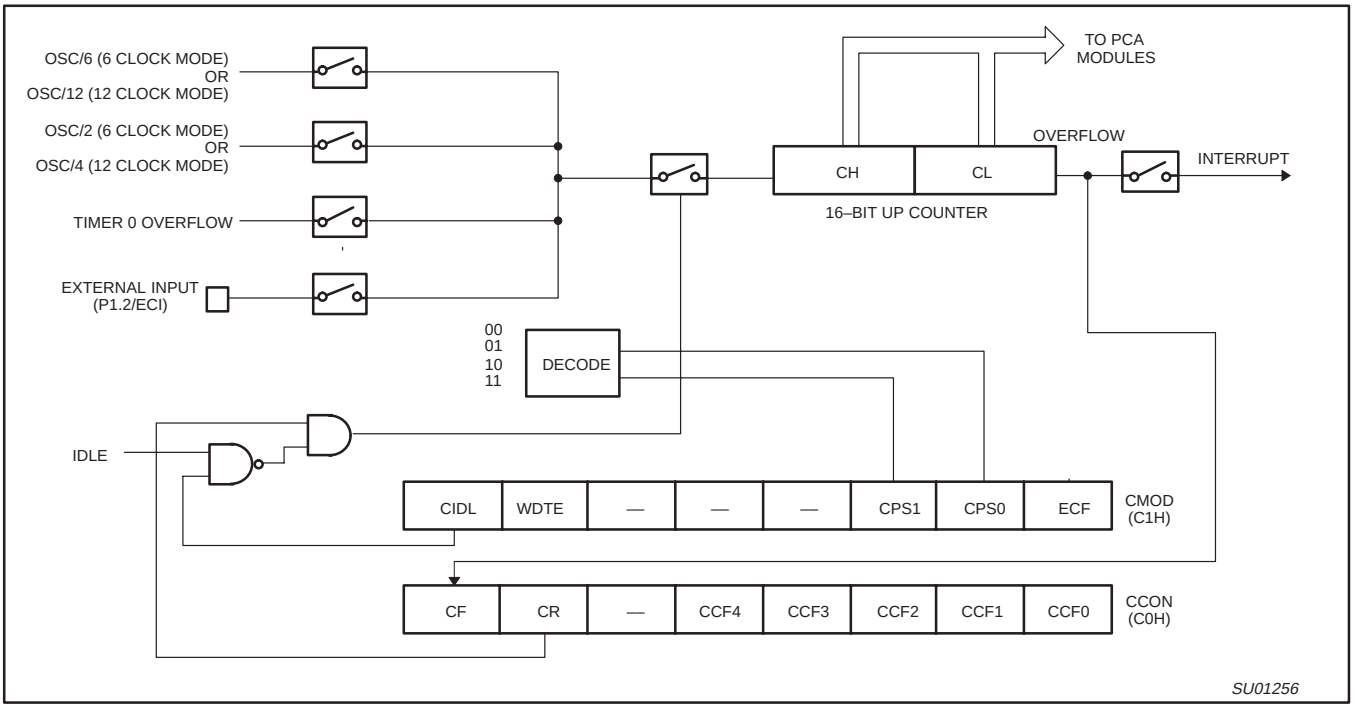


Figure 20. PCA Timer/Counter

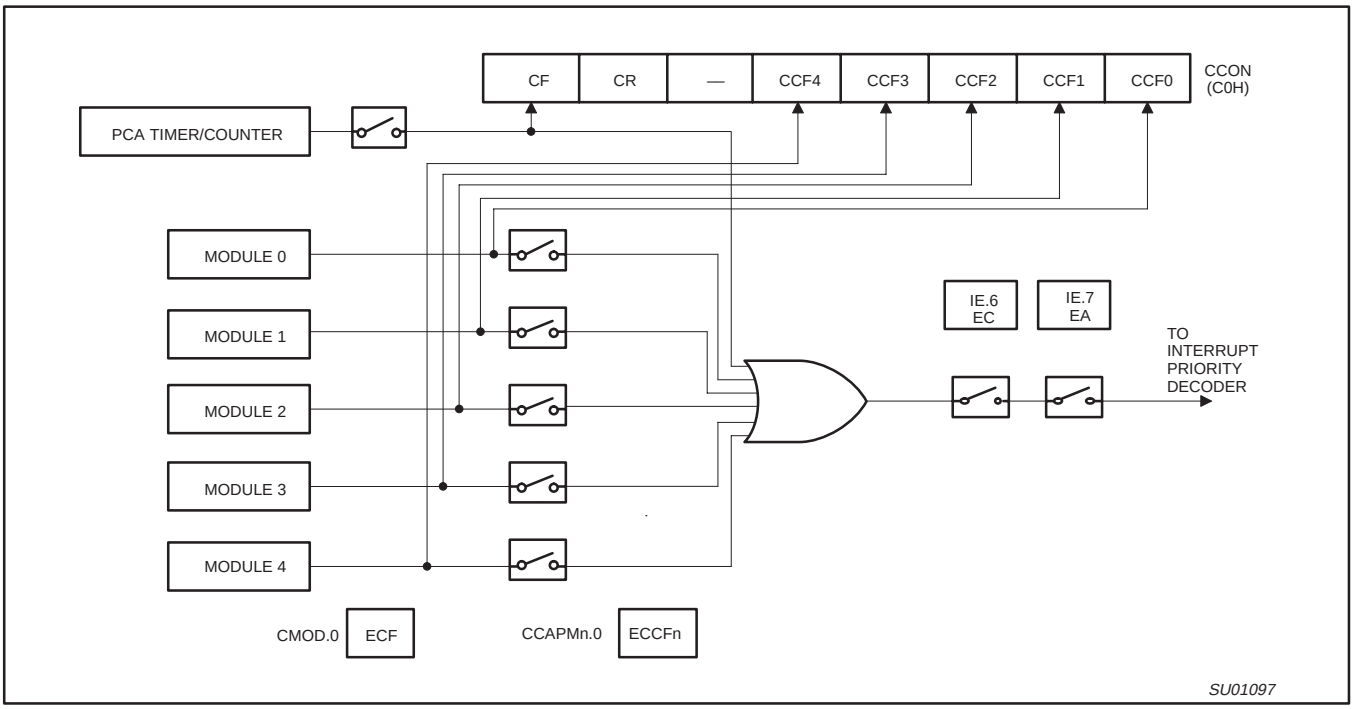


Figure 21. PCA Interrupt System

Expanded Data RAM Addressing

The P87C51RA2/RB2/RC2/RD2 has internal data memory that is mapped into four separate segments: the lower 128 bytes of RAM, upper 128 bytes of RAM, 128 bytes Special Function Register (SFR), and 256 bytes expanded RAM (ERAM) (768 bytes for the RD2).

The four segments are:

1. The Lower 128 bytes of RAM (addresses 00H to 7FH) are directly and indirectly addressable.
2. The Upper 128 bytes of RAM (addresses 80H to FFH) are indirectly addressable only.
3. The Special Function Registers, SFRs, (addresses 80H to FFH) are directly addressable only.
4. The 256/768-bytes expanded RAM (ERAM, 00H – 1FFH/2FFH) are indirectly accessed by move external instruction, MOVX, and with the EXTRAM bit cleared, see Figure 32.

The Lower 128 bytes can be accessed by either direct or indirect addressing. The Upper 128 bytes can be accessed by indirect addressing only. The Upper 128 bytes occupy the same address space as the SFR. That means they have the same address, but are physically separate from SFR space.

When an instruction accesses an internal location above address 7FH, the CPU knows whether the access is to the upper 128 bytes of data RAM or to SFR space by the addressing mode used in the instruction. Instructions that use direct addressing access SFR space. For example:

MOV 0A0H,#data

accesses the SFR at location 0A0H (which is P2). Instructions that use indirect addressing access the Upper 128 bytes of data RAM.

For example:

MOV @R0,acc

where R0 contains 0A0H, accesses the data byte at address 0A0H, rather than P2 (whose address is 0A0H).

The ERAM can be accessed by indirect addressing, with EXTRAM bit cleared and MOVX instructions. This part of memory is physically located on-chip, logically occupies the first 256/768 bytes of external data memory in the P87C51RA2/RB2/RC2/RD2.

With EXTRAM = 0, the ERAM is indirectly addressed, using the MOVX instruction in combination with any of the registers R0, R1 of the selected bank or DPTR. An access to ERAM will not affect ports P0, P3.6 (WR#) and P3.7 (RD#). P2 SFR is output during external addressing. For example, with EXTRAM = 0,

MOVX @R0,acc

where R0 contains 0A0H, accesses the ERAM at address 0A0H rather than external memory. An access to external data memory locations higher than the ERAM will be performed with the MOVX DPTR instructions in the same way as in the standard 80C51, so with P0 and P2 as data/address bus, and P3.6 and P3.7 as write and read timing signals. Refer to Figure 33.

With EXTRAM = 1, MOVX @Ri and MOVX @DPTR will be similar to the standard 80C51. MOVX @ Ri will provide an 8-bit address multiplexed with data on Port 0 and any output port pins can be used to output higher order address bits. This is to provide the external paging capability. MOVX @DPTR will generate a 16-bit address. Port 2 outputs the high-order eight address bits (the contents of DPH) while Port 0 multiplexes the low-order eight address bits (DPL) with data. MOVX @Ri and MOVX @DPTR will generate either read or write signals on P3.6 ($\overline{WR}$) and P3.7 ($\overline{RD}$).

The stack pointer (SP) may be located anywhere in the 256 bytes RAM (lower and upper RAM) internal data memory. The stack may not be located in the ERAM.

AUXR Address = 8EH — Reset Value = xxxx xx00B

Not Bit Addressable

	—	—	—	—	—	—	**EXTRAM**	**AO**
Bit:	7	6	5	4	3	2	1	0

Symbol	Function
AO	Disable/Enable ALE
	AO **Operating Mode**
	0 ALE is emitted at a constant rate of $^1/_6$ the oscillator frequency (12-clock mode; $^1/_3$ f_{OSC} in 6-clock mode).
	1 ALE is active only during off-chip memory access.
EXTRAM	Internal/External RAM access using MOVX @Ri/@DPTR
	EXTRAM **Operating Mode**
	0 Internal ERAM access using MOVX @Ri/@DPTR
	1 External data memory access.
—	Not implemented, reserved for future use*.

NOTE:
*User software should not write 1s to reserved bits. These bits may be used in future 8051 family products to invoke new features. In that case, the reset or inactive value of the new bit will be 0, and its active value will be 1. The value read from a reserved bit is indeterminate.

SU01613

Figure 32. AUXR: Auxiliary Register

DC ELECTRICAL CHARACTERISTICS

T_{amb} = 0 °C to +70 °C or –40 °C to +85 °C; **V_{CC} = 5 V ±10%**; V_{SS} = 0 V (30/33 MHz max. CPU clock)

SYMBOL	PARAMETER	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP[1]	MAX	
V_{IL}	Input low voltage[11]	4.5 V < V_{CC} < 5.5 V	–0.5		0.2 V_{CC}–0.1	V
V_{IH}	Input high voltage (ports 0, 1, 2, 3, $\overline{EA}$)		0.2 V_{CC}+0.9		V_{CC}+0.5	V
V_{IH1}	Input high voltage, XTAL1, RST[11]		0.7 V_{CC}		V_{CC}+0.5	V
V_{OL}	Output low voltage, ports 1, 2, 3 [8]	V_{CC} = 4.5 V; I_{OL} = 1.6 mA[2]	–		0.4	V
V_{OL1}	Output low voltage, port 0, ALE, $\overline{PSEN}$ [7, 8]	V_{CC} = 4.5 V; I_{OL} = 3.2 mA[2]	–		0.4	V
V_{OH}	Output high voltage, ports 1, 2, 3 [3]	V_{CC} = 4.5 V; I_{OH} = –30 µA	V_{CC} – 0.7		–	V
V_{OH1}	Output high voltage (port 0 in external bus mode), ALE[9], $\overline{PSEN}$[3]	V_{CC} = 4.5 V; I_{OH} = –3.2 mA	V_{CC} – 0.7		–	V
I_{IL}	Logical 0 input current, ports 1, 2, 3	V_{IN} = 0.4 V	–1		–50	µA
I_{TL}	Logical 1-to-0 transition current, ports 1, 2, 3[6]	V_{IN} = 2.0 V; See note 4	–		–650	µA
I_{LI}	Input leakage current, port 0	0.45 < V_{IN} < V_{CC} – 0.3	–		±10	µA
I_{CC}	Power supply current					
	Active mode (see Note 5)					
	Idle mode (see Note 5)					
	Power-down mode or clock stopped (see Figure 46 for conditions)	T_{amb} = 0 °C to 70 °C		2	30	µA
		T_{amb} = –40 °C to +85 °C		3	50	µA
V_{RAM}	RAM keep-alive voltage		1.2			V
R_{RST}	Internal reset pull-down resistor		40		225	kΩ
C_{IO}	Pin capacitance[10] (except $\overline{EA}$)		–		15	pF

NOTES:

1. Typical ratings are not guaranteed. The values listed are at room temperature, 5 V.
2. Capacitive loading on ports 0 and 2 may cause spurious noise to be superimposed on the V_{OL}s of ALE and ports 1 and 3. The noise is due to external bus capacitance discharging into the port 0 and port 2 pins when these pins make 1-to-0 transitions during bus operations. In the worst cases (capacitive loading > 100 pF), the noise pulse on the ALE pin may exceed 0.8 V. In such cases, it may be desirable to qualify ALE with a Schmitt Trigger, or use an address latch with a Schmitt Trigger STROBE input. I_{OL} can exceed these conditions provided that no single output sinks more than 5 mA and no more than two outputs exceed the test conditions.
3. Capacitive loading on ports 0 and 2 may cause the V_{OH} on ALE and $\overline{PSEN}$ to momentarily fall below the V_{CC}–0.7 specification when the address bits are stabilizing.
4. Pins of ports 1, 2 and 3 source a transition current when they are being externally driven from 1 to 0. The transition current reaches its maximum value when V_{IN} is approximately 2 V.
5. See Figures 43 through 46 for I_{CC} test conditions and Figure 41 for I_{CC} vs. Frequency.
   12-clock mode characteristics:
   Active mode (operating): I_{CC} = 1.0 mA + 1.1 mA × FREQ.[MHz]
   Active mode (reset): I_{CC} = 7.0 mA + 0.6 mA × FREQ.[MHz]
   Idle mode: I_{CC} = 1.0 mA + 0.22 mA × FREQ.[MHz]
6. This value applies to T_{amb} = 0°C to +70°C. For T_{amb} = –40°C to +85°C, I_{TL} = –750 µA.
7. Load capacitance for port 0, ALE, and $\overline{PSEN}$ = 100 pF, load capacitance for all other outputs = 80 pF.
8. Under steady state (non-transient) conditions, I_{OL} must be externally limited as follows:
   Maximum I_{OL} per port pin: 15 mA (*NOTE: This is 85 °C specification.)
   Maximum I_{OL} per 8-bit port: 26 mA
   Maximum total I_{OL} for all outputs: 71 mA
   If I_{OL} exceeds the test condition, V_{OL} may exceed the related specification. Pins are not guaranteed to sink current greater than the listed test conditions.
9. ALE is tested to V_{OH1}, except when ALE is off then V_{OH} is the voltage specification.
10. Pin capacitance is characterized but not tested. Pin capacitance is less than 25 pF. Pin capacitance of ceramic package is less than 15 pF (except $\overline{EA}$ is 25 pF).
11. To improve noise rejection a nominal 100 ns glitch rejection circuitry has been added to the RST pin, and a nominal 15 ns glitch rejection circuitry has been added to the $\overline{INT0}$ and $\overline{INT1}$ pins. Previous devices provided only an inherent 5 ns of glitch rejection.

AC ELECTRICAL CHARACTERISTICS (6-CLOCK MODE, 2.7 V TO 5.5 V OPERATION)

T_{amb} = 0 °C to +70 °C or –40 °C to +85 °C ; V_{CC}=2.7 V to 5.5 V, V_{SS} = 0 V[1,2,3,4,5]

Symbol	Figure	Parameter	Limits		16 MHz Clock		Unit
			MIN	MAX	MIN	MAX	
$1/t_{CLCL}$	38	Oscillator frequency	0	16			MHz
t_{LHLL}	34	ALE pulse width	t_{CLCL}–10		52.5		ns
t_{AVLL}	34	Address valid to ALE low	0.5 t_{CLCL} –15		16.25		ns
t_{LLAX}	34	Address hold after ALE low	0.5 t_{CLCL} –25		6.25		ns
t_{LLIV}	34	ALE low to valid instruction in		2 t_{CLCL} –55		70	ns
t_{LLPL}	34	ALE low to $\overline{PSEN}$ low	0.5 t_{CLCL} –15		16.25		ns
t_{PLPH}	34	$\overline{PSEN}$ pulse width	1.5 t_{CLCL} –15		78.75		ns
t_{PLIV}	34	$\overline{PSEN}$ low to valid instruction in		1.5 t_{CLCL} –55		38.75	ns
t_{PXIX}	34	Input instruction hold after $\overline{PSEN}$	0		0		ns
t_{PXIZ}	34	Input instruction float after $\overline{PSEN}$		0.5 t_{CLCL} –10		21.25	ns
t_{AVIV}	34	Address to valid instruction in		2.5 t_{CLCL} –50		101.25	ns
t_{PLAZ}	34	$\overline{PSEN}$ low to address float		10		10	ns
Data Memory							
t_{RLRH}	35	$\overline{RD}$ pulse width	3 t_{CLCL} –25		162.5		ns
t_{WLWH}	36	$\overline{WR}$ pulse width	3 t_{CLCL} –25		162.5		ns
t_{RLDV}	35	$\overline{RD}$ low to valid data in		2.5 t_{CLCL} –50		106.25	ns
t_{RHDX}	35	Data hold after $\overline{RD}$	0		0		ns
t_{RHDZ}	35	Data float after $\overline{RD}$		t_{CLCL} –20		42.5	ns
t_{LLDV}	35	ALE low to valid data in		4 t_{CLCL} –55		195	ns
t_{AVDV}	35	Address to valid data in		4.5 t_{CLCL} –50		231.25	ns
t_{LLWL}	35, 36	ALE low to $\overline{RD}$ or $\overline{WR}$ low	1.5 t_{CLCL} –20	1.5 t_{CLCL} +20	73.75	113.75	ns
t_{AVWL}	35, 36	Address valid to $\overline{WR}$ low or $\overline{RD}$ low	2 t_{CLCL} –20		105		ns
t_{QVWX}	36	Data valid to $\overline{WR}$ transition	0.5 t_{CLCL} –30		1.25		ns
t_{WHQX}	36	Data hold after $\overline{WR}$	0.5 t_{CLCL} –20		11.25		ns
t_{QVWH}	36	Data valid to $\overline{WR}$ high	3.5 t_{CLCL} –10		208.75		ns
t_{RLAZ}	35	$\overline{RD}$ low to address float		0		0	ns
t_{WHLH}	35, 36	$\overline{RD}$ or $\overline{WR}$ high to ALE high	0.5 t_{CLCL} –15	0.5 t_{CLCL} +15	16.25	46.25	ns
External Clock							
t_{CHCX}	38	High time	0.4 t_{CLCL}	t_{CLCL} – t_{CLCX}			ns
t_{CLCX}	38	Low time	0.4 t_{CLCL}	t_{CLCL} – t_{CHCX}			ns
t_{CLCH}	38	Rise time		5			ns
t_{CHCL}	38	Fall time		5			ns
Shift register							
t_{XLXL}	37	Serial port clock cycle time	6 t_{CLCL}		375		ns
t_{QVXH}	37	Output data setup to clock rising edge	5 t_{CLCL} –25		287.5		ns
t_{XHQX}	37	Output data hold after clock rising edge	t_{CLCL} –15		47.5		ns
t_{XHDX}	37	Input data hold after clock rising edge	0		0		ns
t_{XHDV}	37	Clock rising edge to input data valid[6]		5 t_{CLCL} –133		179.5	ns

NOTES:
1. Parameters are valid over operating temperature range unless otherwise specified.
2. Load capacitance for port 0, ALE, and $\overline{PSEN}$=100 pF, load capacitance for all outputs = 80 pF
3. Interfacing the microcontroller to devices with float time up to 45ns is permitted. This limited bus contention will not cause damage to port 0 drivers.
4. Parts are guaranteed by design to operate down to 0 Hz.
5. Data shown in the table are the best mathematical models for the set of measured values obtained in tests. If a particular parameter calculated at a customer specified frequency has a negative value, it should be considered equal to zero.
6. Below 16 MHz this parameter is 4 t_{CLCL} – 133

EXPLANATION OF THE AC SYMBOLS

Each timing symbol has five characters. The first character is always 't' (= time). The other characters, depending on their positions, indicate the name of a signal or the logical status of that signal. The designations are:

A – Address
C – Clock
D – Input data
H – Logic level high
I – Instruction (program memory contents)
L – Logic level low, or ALE
P – $\overline{\text{PSEN}}$
Q – Output data
R – $\overline{\text{RD}}$ signal
t – Time
V – Valid
W – $\overline{\text{WR}}$ signal
X – No longer a valid logic level
Z – Float

Examples: t_{AVLL} = Time for address valid to ALE low.
t_{LLPL} =Time for ALE low to $\overline{\text{PSEN}}$ low.

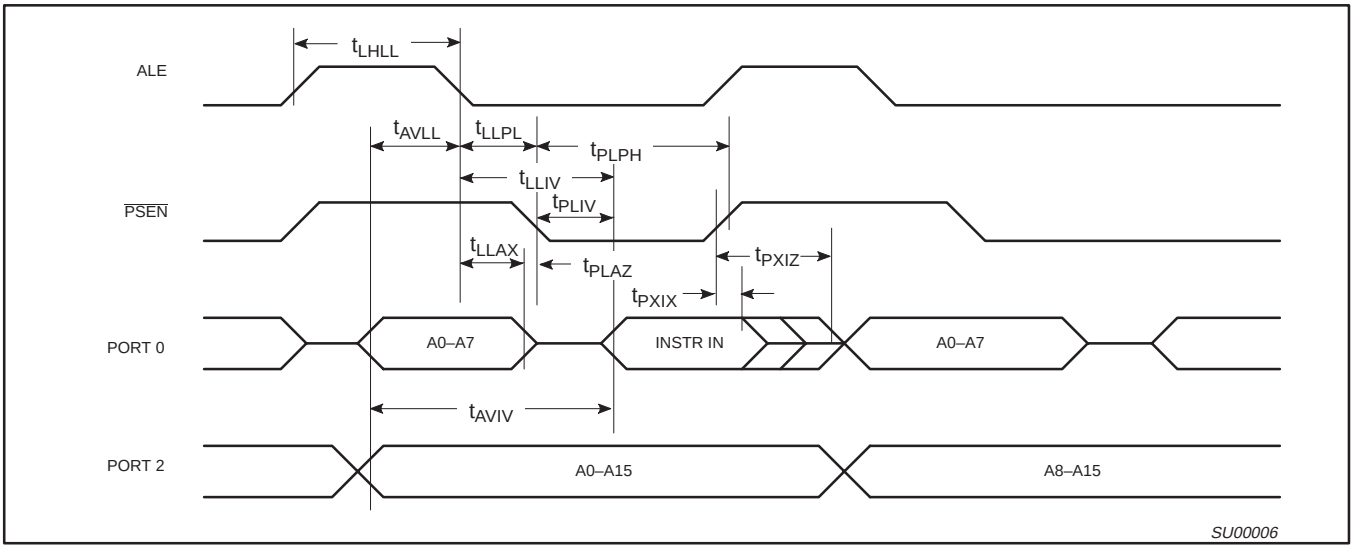


Figure 34. External Program Memory Read Cycle

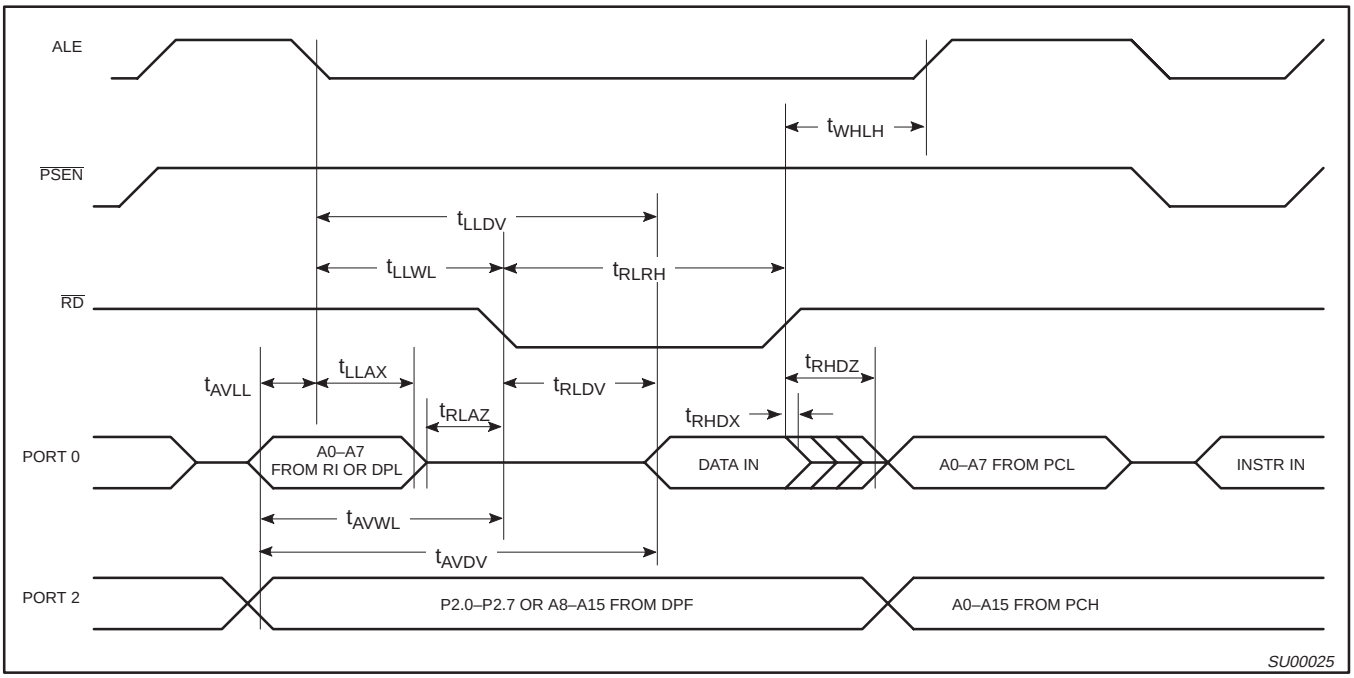


Figure 35. External Data Memory Read Cycle

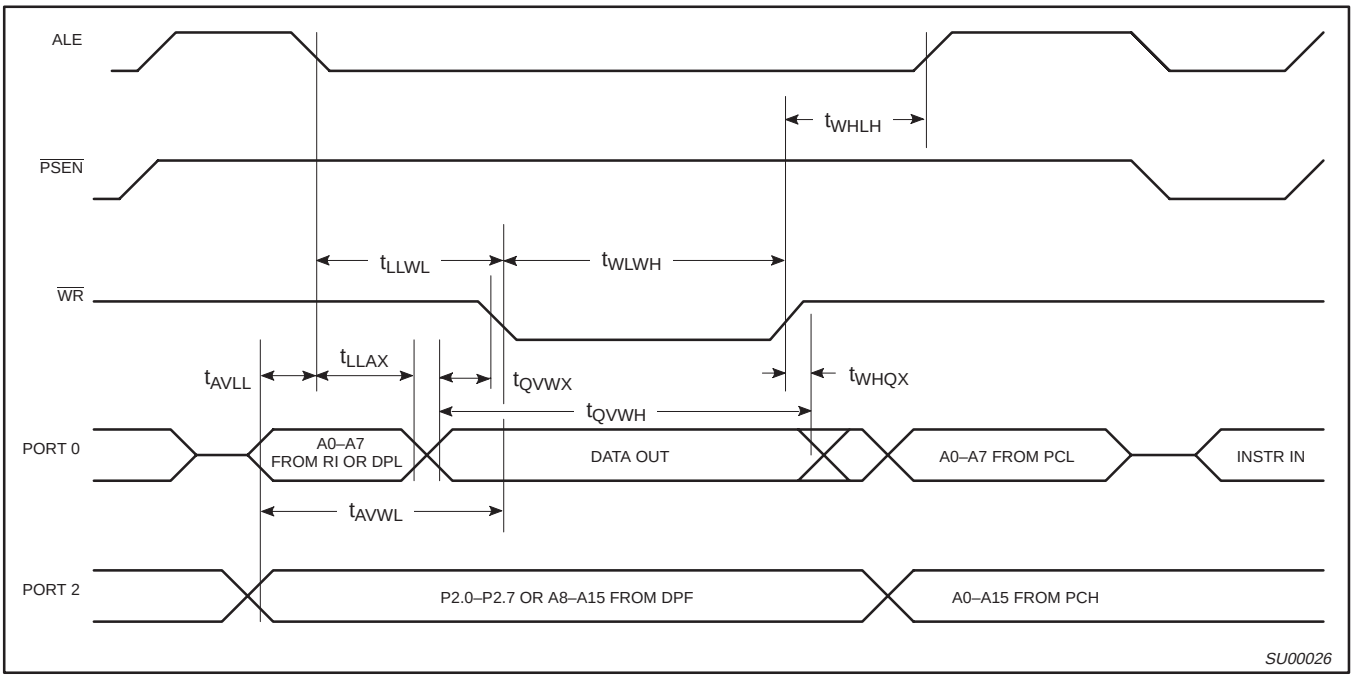


Figure 36. External Data Memory Write Cycle

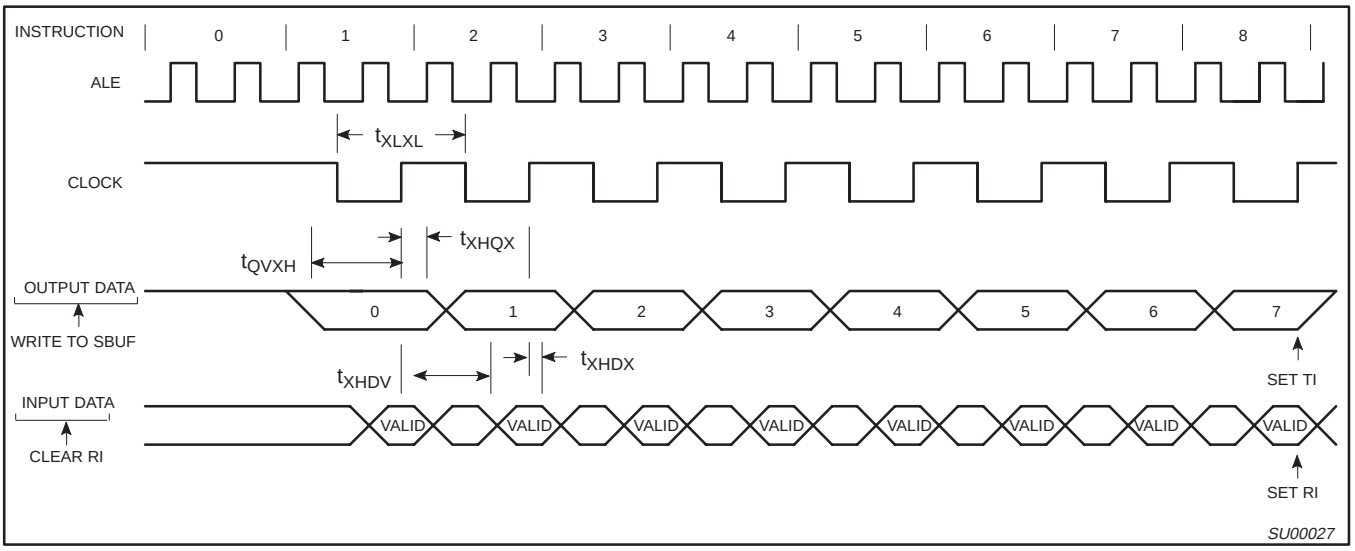


Figure 37. Shift Register Mode Timing

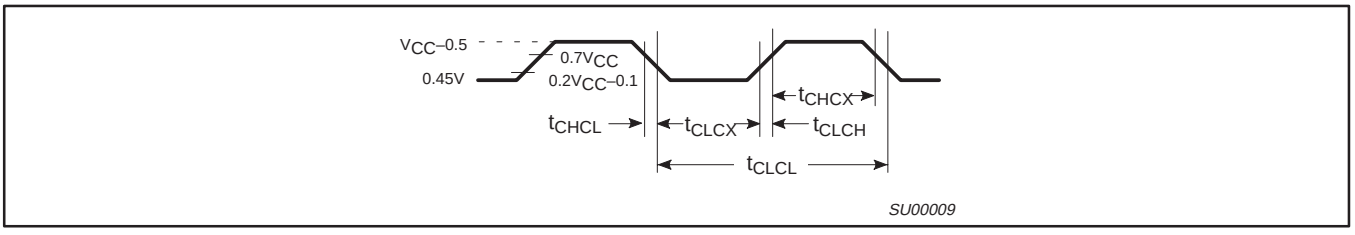


Figure 38. External Clock Drive

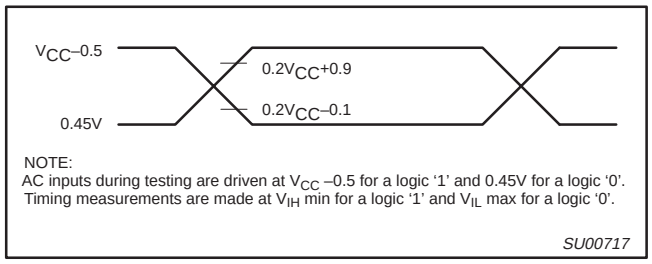


Figure 39. AC Testing Input/Output

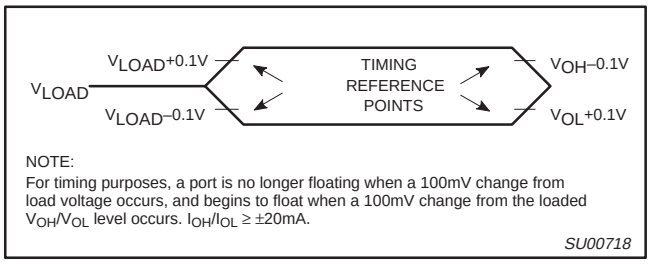


Figure 40. Float Waveform

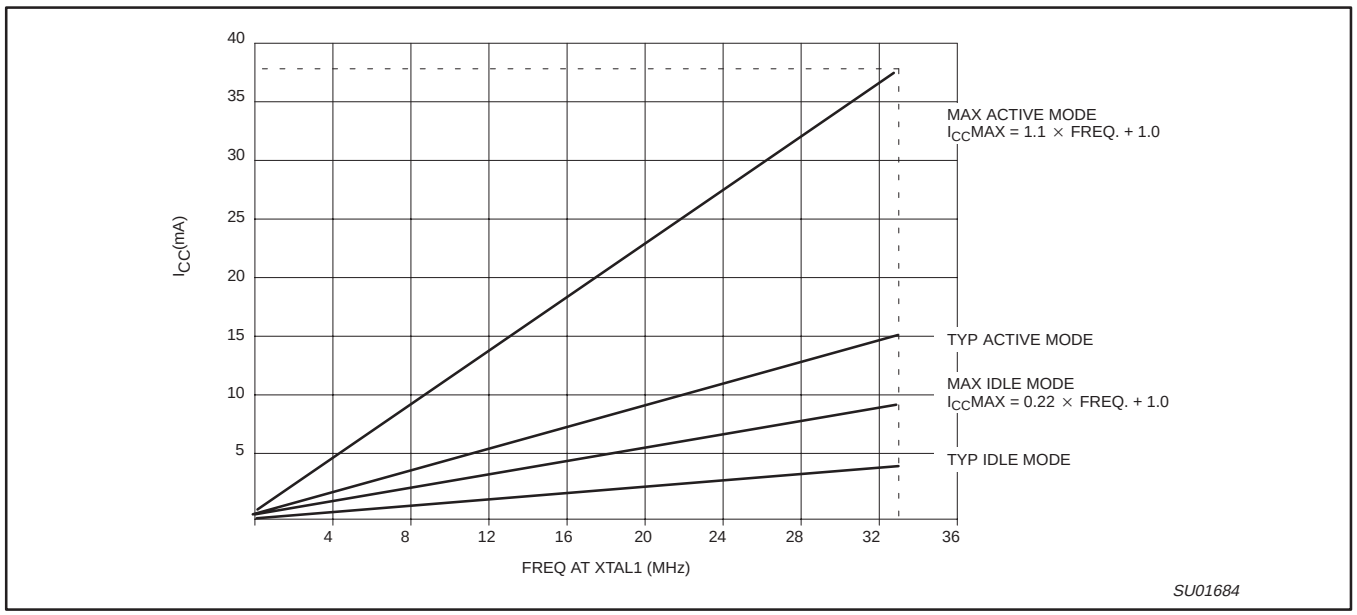


Figure 41. I_{CC} vs. FREQ for 12-clock operation
Valid only within frequency specifications of the specified operating voltage

```
/*
##      as31 version V2.10           / *js* /
##
##
##      source file:  idd_ljmp1.asm
##        list file:  idd_ljmp1.lst   created Fri Apr 20 15:51:40 2001
##
#############################################################
#0000                # AUXR  equ 08Eh
#0000                # CKCON equ 08Fh
                     #
                     #
#0000                # org 0
                     #
                     # LJMP_LABEL:
0000 /75;/8E;/01;    #          MOV     AUXR,#001h   ; turn off ALE
0003 /02;/FF;/FD;    #          LJMP    LJMP_LABEL   ; jump to end of address space
0005 /00;            #          NOP
                     #
#FFFD                # org 0fffdh
                     #
                     # LJMP_LABEL:
                     #
FFFD /02;/FD;FF;     #          LJMP LJMP_LABEL
                     # ;        NOP
                     #
                     #
*/"
```

SU01499

Figure 42. Source code used in measuring I_{DD} operational

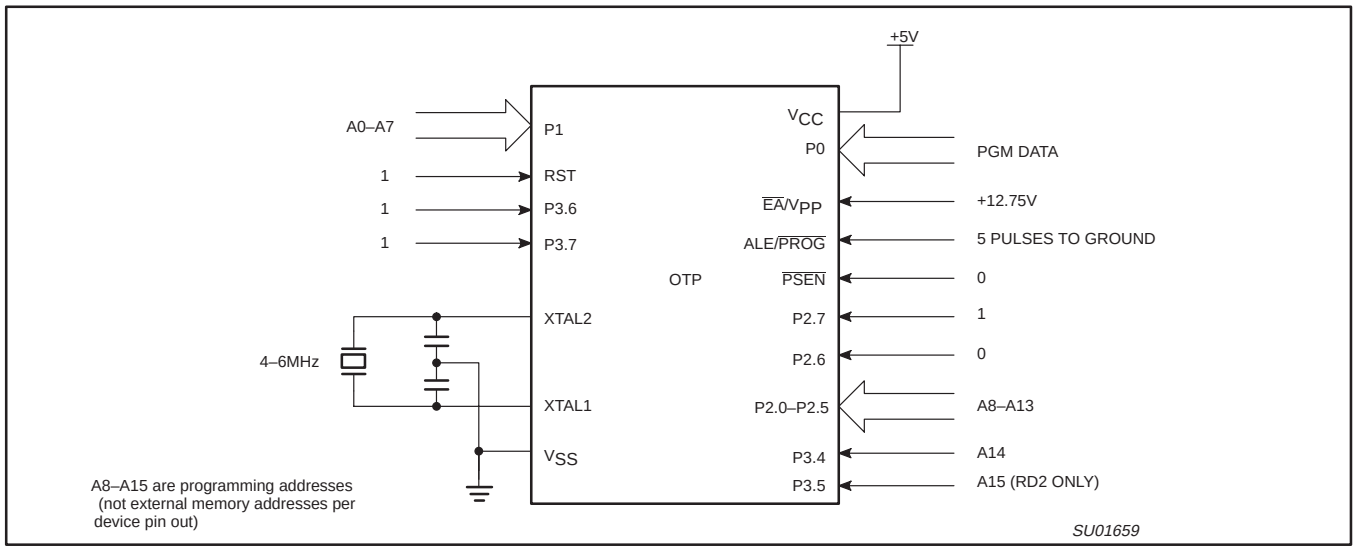


Figure 47. Programming Configuration

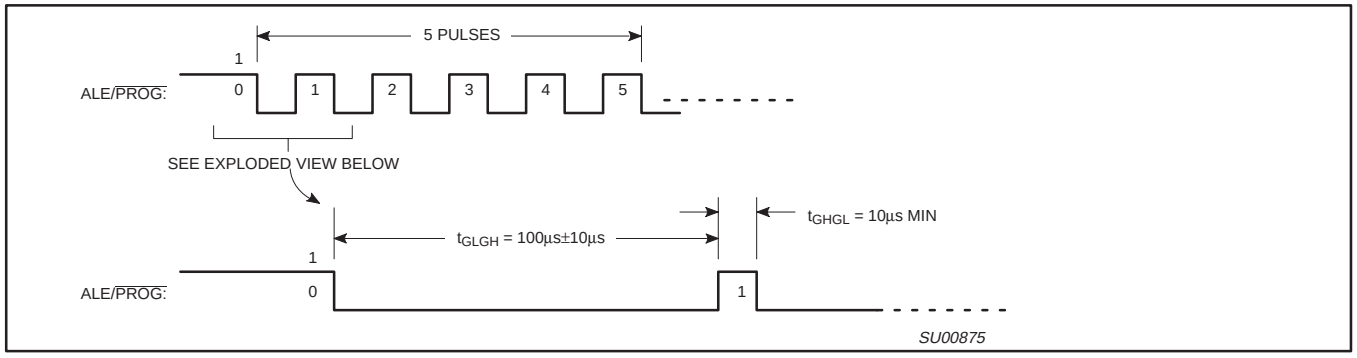


Figure 48. $\overline{\text{PROG}}$ Waveform

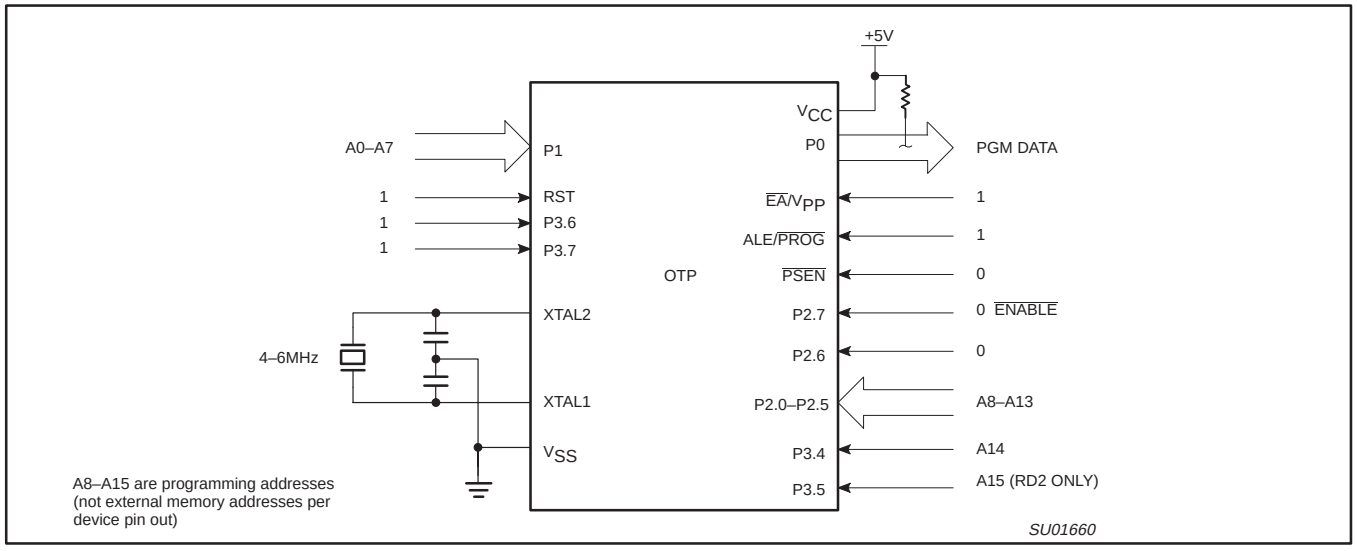
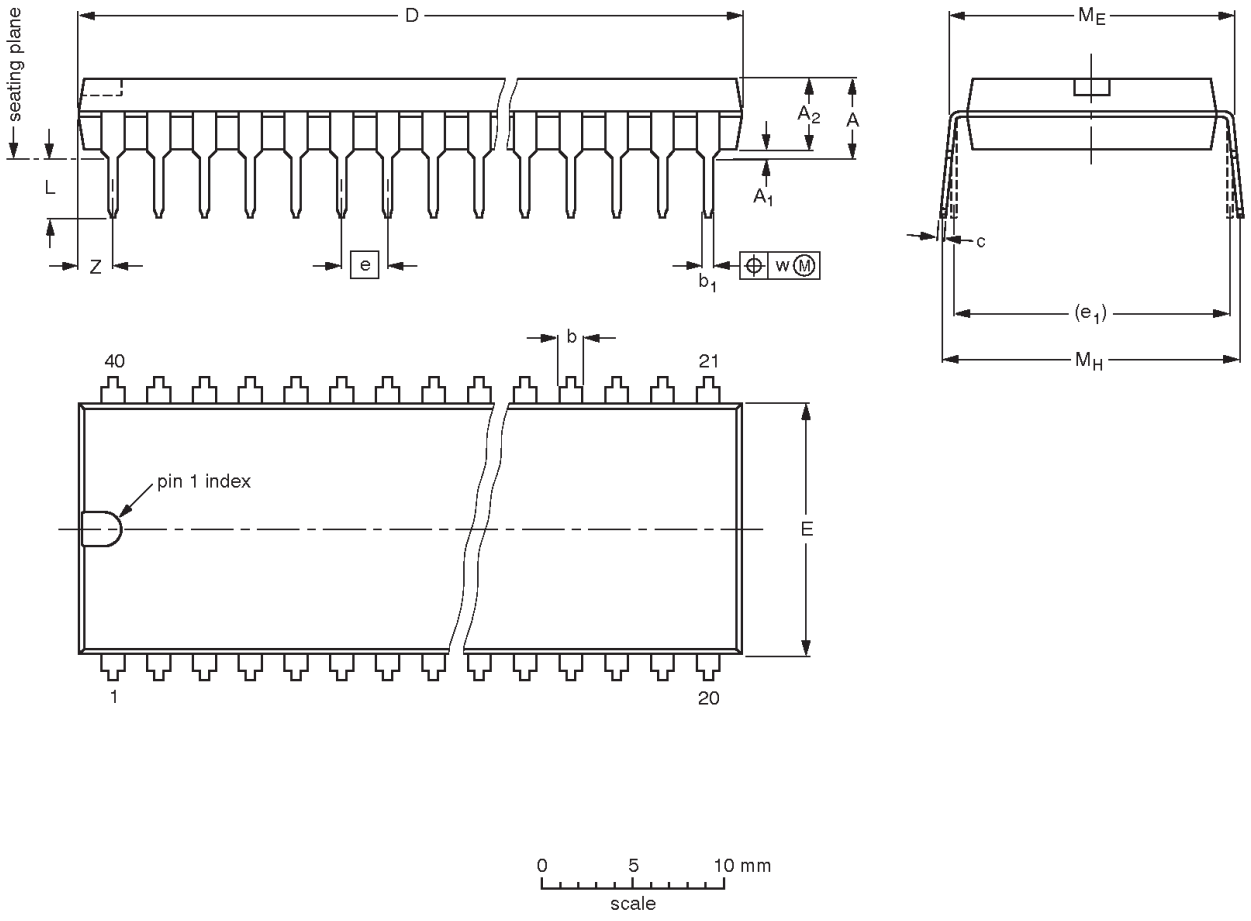


Figure 49. Program Verification

DIP40: plastic dual in-line package; 40 leads (600 mil) SOT129-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

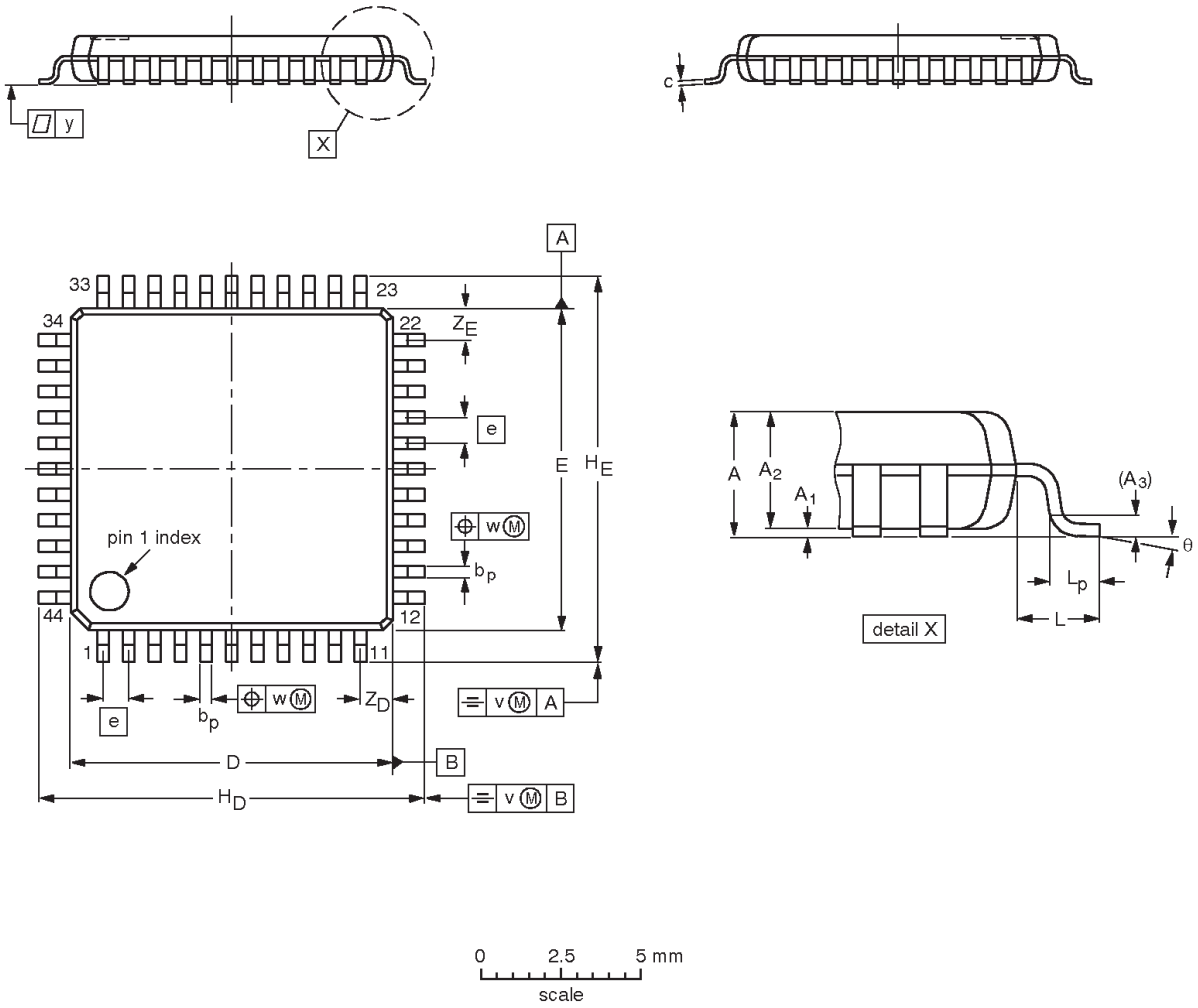
UNIT	A max.	A_1 min.	A_2 max.	b	b_1	c	D (1)	E (1)	e	e_1	L	M_E	M_H	w	Z (1) max.
mm	4.7	0.51	4.0	1.70 1.14	0.53 0.38	0.36 0.23	52.50 51.50	14.1 13.7	2.54	15.24	3.60 3.05	15.80 15.24	17.42 15.90	0.254	2.25
inches	0.19	0.020	0.16	0.067 0.045	0.021 0.015	0.014 0.009	2.067 2.028	0.56 0.54	0.10	0.60	0.14 0.12	0.62 0.60	0.69 0.63	0.01	0.089

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT129-1	051G08	MO-015	SC-511-40			~~95-01-14~~ 99-12-27

LQFP44: plastic low profile quad flat package; 44 leads; body 10 x 10 x 1.4 mm SOT389-1



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(1)}$	e	H_D	H_E	L	L_p	v	w	y	$Z_D^{(1)}$	$Z_E^{(1)}$	θ
mm	1.6	0.15 0.05	1.45 1.35	0.25	0.45 0.30	0.20 0.12	10.1 9.9	10.1 9.9	0.8	12.15 11.85	12.15 11.85	1	0.75 0.45	0.2	0.2	0.1	1.14 0.85	1.14 0.85	7^o 0^o

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT389-1	136E08	MS-026				~~00-01-19~~ 02-06-07

REVISION HISTORY

Rev	Date	Description
_3	20030124	**Product data (9397 750 10994); ECN 853-2391 29335 dated 07 Jan 2003.** Modifications: ● Updated ordering information table.
_2	20021028	**Product data (9397 750 10393); ECN 853-2391 29117 dated 28 Oct 2002.**

Data sheet status

Level	Data sheet status [1]	Product status [2] [3]	Definitions
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
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[3] For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

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